

PATENT

Serial No. 10/577,295

Amendment in Reply to Office Action mailed on February 25, 2009

IN THE ABSTRACT

Please delete the current Abstract in its entirety and  
substitute therefor the enclosed New Abstract.

NEW ABSTRACT

A camera module includes a semiconductor housing that contains a solid-state image sensor with a radiation-sensitive surface area, and an optical element located above the solid-state sensor and which forms a shield against laterally scattered radiation. The optical element includes a disk-shaped body with a primary radiation-opaque area and a secondary radiation-transparent area located within the primary area, of which a surface close to the sensor is smaller than a surface more remote from the sensor. The optical element further includes a transparent plate of which two sides are covered with a radiation-opaque layer which is provided with an aperture. In the aperture, the layer close to the sensor has a smaller surface than the aperture in the layer located remote from the sensor.